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ABSTRACT OF THE DISCLOSURE

An apparatus for connecting one substrate, such as flip-chip type semiconductor die, to an opposing substrate, such as a silicon wafer, printed circuit board, or other substrate. Each substrate has a plurality of conductive bumps on its facing surface wherein the conductive bumps on each substrate are the mirror-image of the other substrate. The substrates are attached to one another in a manner in which the conductive bumps on one substrate form an electrical contact with its respective conductive bumps on the opposing substrate without mechanical attachment.

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